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(54) **EARPHONE MODULE**

(71) Applicant: **Merry Electronics Co., Ltd.**, Taichung (TW)

(72) Inventors: **Jui-Hsien Chien**, Taichung (TW);
Wan-Hsuan Weng, Taichung (TW);
Ying-Ying Peng, Taichung (TW)

(73) Assignee: **Merry Electronics Co., Ltd.**, Taichung (TW)

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(57) **ABSTRACT**

An earphone module includes a first circuit board. The first circuit board includes a touch panel layer, a grounding layer, an antenna layer and a touch circuit layer assembly. The grounding layer is disposed apart from and below the touch panel layer. The antenna layer includes an antenna flat portion, an antenna feed wire and an antenna short-circuit wire. The antenna flat portion is disposed apart from and below the grounding layer, and the antenna feed wire and the antenna short-circuit wire are connected to the antenna flat portion. The touch circuit layer assembly is disposed apart from and below the antenna flat portion and includes a touch chip. The touch panel layer is electrically connected to the touch chip.

